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Thin Films—Stresses and Mechanical Properties XI

Editors: Thomas E. Buchheit, Andrew M. Minor, Ralph Spolenak and Kazuki Takashima

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Thin Films—Stresses and Mechanical Properties XI

Symposium held March 28–April 1, 2005, San Francisco, California, U.S.A.

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PREFACE

This proceedings volume reports on research presented at Symposium O, "Thin Films—Stresses and Mechanical Properties XI," held March 28–April 1 at the 2005 MRS Spring Meeting in San Francisco, California. This 11th symposium in the continuing series, held at 1-1/2 year intervals, provided a forum for an exchange of ideas between researchers who are interested in the mechanical behavior of thin films, broadly applied to their materials choice or methodology. This proceedings contains several papers discussing stress-related phenomena in thin films for a wide range of materials, including brittle, metallic, polymeric and biological materials. Over 100 submissions were selected for presentation at the Meeting, and 65 papers are included in these proceedings.

Thomas E. Buchheit
Andrew M. Minor
Ralph Spolenak
Kazuki Takashima

September 2005

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